

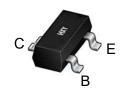
Features

Collector Current: I_C=0.6A

Power Dissipation of 300mw

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
SST4401T116	SOT-23	2X	3000





SOT-23

Maximum Ratings (Ta=25°C unless otherwise noted)

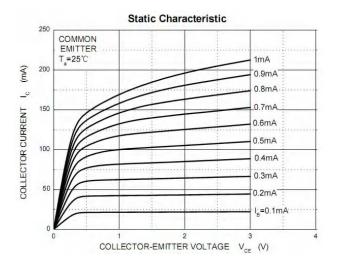
Parameter	Symbol	Limit	Unit
Collector-Base Voltage	V _{CBO}	60	V
Collector-Emitter Voltage	V _{CEO}	40	V
Emitter-Base Voltage	V _{EBO}	6	V
Collector Current	I _C	600	mA
Collector Power Dissipation	P _c	300	mW
Thermal Resistance From Junction To Ambient	R _{OJA}	417	°C/W
Junction Temperature	T _j	150	°C
Storage Temperature	T _{stg}	-55∼+150	$^{\circ}$

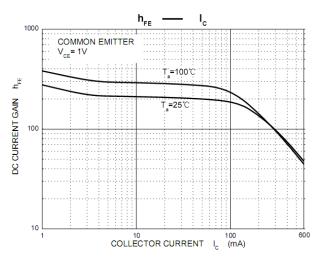


Electrcal Charcteristics (Ta=25°C unless otherwise specified)

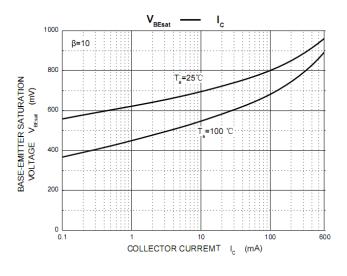
Parameter	Symbol	Test Conditions	Min	Max	Unit
Collector-base breakdown voltage	V _{(BR)CBO}	I _C =100μA,I _E =0	60		V
Collector-emitter breakdown voltage	V _{(BR)CEO}	I _C =1mA,I _B =0	40		V
Emitter-base breakdown voltage	V _{(BR)EBO}	I _E =100μA ,I _C =0	6		V
Collector cut-off current	I _{CBO}	V _{CB} =50V,I _E =0		0.1	μA
Collector cut-off current	I _{CEX}	Vce=35V, Veb=0.4V		0.1	μA
Emitter cut-off current	I _{EBO}	V _{EB} =5V,I _C =0		0.1	μA
	h _{FE1}	V _{CE} =1V, I _C =0.1mA	20		
	h _{FE2}	V _{CE} =1V, I _C =1mA	40		
DC current gain	h _{FE3}	V _{CE} =1V, I _C =10mA	80		
	h _{FE4}	V _{CE} =1V, I _C =150mA	100	300	
	h _{FE5}	V _{CE} =2V, I _C =500mA	40		
Collector emitter esturation valtage	Vorces			0.4	V
Collector-emitter saturation voltage	V _{CE(sat)}	I _C =500mA,I _B =50mA		0.75	V
Page emitter acturation voltage	V _{BE(sat)}	I _C =150mA,I _B =15mA		0.95	V
Base-emitter saturation voltage		I _C =500mA,I _B =50mA		1.2	V
Transition frequency	f _T	V _{CE} =10V, I _C =20mA,f =100MHz 250			MHz
Delay time	t _d	Vcc=30V, VBE(off)=-2V		15	ns
Rise time	t _r	Ic=150mA , Iв1=15mA		20	ns
Storage time	t _s	Vcc=30V, Ic=150mA		225	ns
Fall time	t _f	I _{B1} =I _{B2} =15mA		60	ns

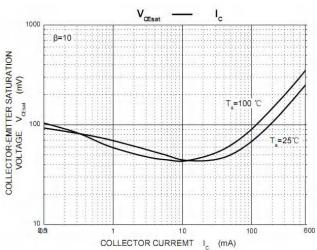
Typical Characteristics

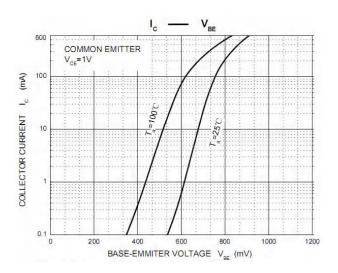


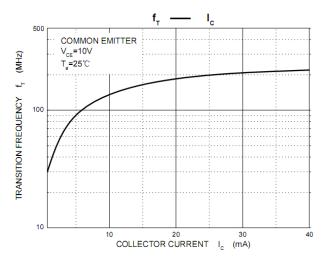


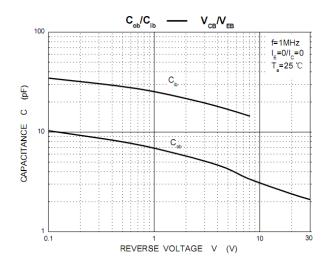


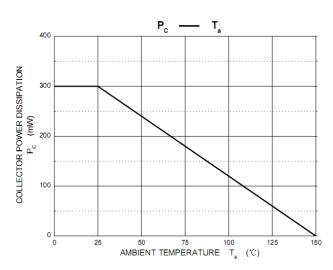






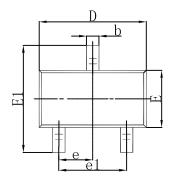


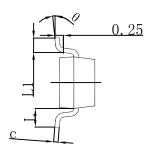


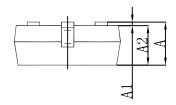




SOT-23 Package Outline Dimensions

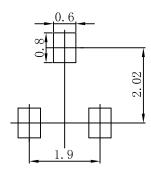






Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

SOT-23 Suggested Pad Layout



Note:

- 1. Controlling dimension: in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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